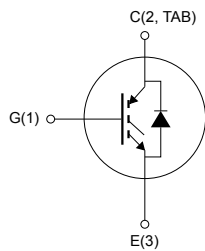
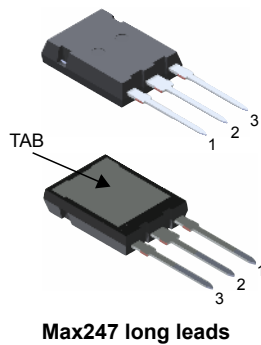



## Automotive-grade trench gate field-stop, 650 V, 120 A, low-loss, M series IGBT in a Max247 long leads package



NG1E3C2T



### Features

- AEC-Q101 qualified 
- 6  $\mu$ s of short-circuit withstand time
- $V_{CE(sat)} = 1.65$  V (typ.) @  $I_C = 120$  A
- Tight parameter distribution
- Safer paralleling
- Positive  $V_{CE(sat)}$  temperature coefficient
- Low thermal resistance
- Soft and very fast recovery antiparallel diode
- Maximum junction temperature:  $T_J = 175$  °C

### Applications

- Heating system
- HV battery disconnect and fire-off system
- Main inverter (electric traction)

### Description

This device is an IGBT developed using an advanced proprietary trench gate field-stop structure. The device is part of the M series IGBTs, which represent an optimal balance between inverter system performance and efficiency where the low-loss and the short-circuit functionality is essential. Furthermore, the positive  $V_{CE(sat)}$  temperature coefficient and the tight parameter distribution result in safer paralleling operation.

#### Product status link

[STGYA120M65DF2AG](#)

#### Product summary

|                   |                   |
|-------------------|-------------------|
| <b>Order code</b> | STGYA120M65DF2AG  |
| <b>Marking</b>    | G120M65DF2AG      |
| <b>Package</b>    | Max247 long leads |
| <b>Packing</b>    | Tube              |

# 1 Electrical ratings

**Table 1. Absolute maximum ratings**

| Symbol         | Parameter                                      | Value      | Unit |
|----------------|--|------------|------|
| $V_{CES}$      | Collector-emitter voltage ( $V_{GE} = 0$ V)    | 650        | V    |
| $I_C^{(1)}$    | Continuous collector current at $T_C = 25$ °C  | 160        | A    |
| $I_C$          | Continuous collector current at $T_C = 100$ °C | 120        |      |
| $I_{CP}^{(2)}$ | Pulsed collector current                       | 360        | A    |
| $V_{GE}$       | Gate-emitter voltage                           | ±20        | V    |
| $I_F^{(1)}$    | Continuous forward current at $T_C = 25$ °C    | 160        | A    |
| $I_F$          | Continuous forward current at $T_C = 100$ °C   | 120        |      |
| $I_{FP}^{(2)}$ | Pulsed forward current                         | 360        | A    |
| $P_{TOT}$      | Total power dissipation at $T_C = 25$ °C       | 625        | W    |
| $T_{STG}$      | Storage temperature range                      | -55 to 150 | °C   |
| $T_J$          | Operating junction temperature range           | -55 to 175 |      |

1. Current level is limited by bond wires.
2. Pulse width limited by maximum junction temperature.

**Table 2. Thermal data**

| Symbol     | Parameter                               | Value | Unit |
|------------|---|-------|------|
| $R_{thJC}$ | Thermal resistance, junction-case IGBT  | 0.24  | °C/W |
| $R_{thJC}$ | Thermal resistance, junction-case diode | 0.6   |      |
| $R_{thJA}$ | Thermal resistance, junction-ambient    | 50    |      |

## 2 Electrical characteristics

$T_C = 25\text{ °C}$  unless otherwise specified

**Table 3. Static characteristics**

| Symbol        | Parameter                            | Test conditions   | Min. | Typ. | Max.      | Unit          |
|---------------|--------------------------------------|---|------|------|-----------|---------------|
| $V_{(BR)CES}$ | Collector-emitter breakdown voltage  | $V_{GE} = 0\text{ V}, I_C = 250\text{ }\mu\text{A}$             | 650  |      |           | V             |
| $V_{CE(sat)}$ | Collector-emitter saturation voltage | $V_{GE} = 15\text{ V}, I_C = 120\text{ A}$                      |      | 1.65 | 2.15      | V             |
|               |                                      | $V_{GE} = 15\text{ V}, I_C = 120\text{ A}, T_J = 125\text{ °C}$ |      | 1.95 |           |               |
|               |                                      | $V_{GE} = 15\text{ V}, I_C = 120\text{ A}, T_J = 175\text{ °C}$ |      | 2.1  |           |               |
| $V_F$         | Forward on-voltage                   | $I_F = 120\text{ A}$  |      | 1.9  | 2.6       | V             |
|               |                                      | $I_F = 120\text{ A}, T_J = 125\text{ °C}$                       |      | 1.7  |           |               |
|               |                                      | $I_F = 120\text{ A}, T_J = 175\text{ °C}$                       |      | 1.6  |           |               |
| $V_{GE(th)}$  | Gate threshold voltage               | $V_{CE} = V_{GE}, I_C = 2\text{ mA}$                            | 5    | 6    | 7         | V             |
| $I_{CES}$     | Collector cut-off current            | $V_{GE} = 0\text{ V}, V_{CE} = 650\text{ V}$                    |      |      | 100       | $\mu\text{A}$ |
| $I_{GES}$     | Gate-emitter leakage current         | $V_{CE} = 0\text{ V}, V_{GE} = \pm 20\text{ V}$                 |      |      | $\pm 250$ | $\mu\text{A}$ |

**Table 4. Dynamic characteristics**

| Symbol    | Parameter                    | Test conditions   | Min. | Typ.  | Max. | Unit |
|-----------|------------------------------|---|------|-------|------|------|
| $C_{ies}$ | Input capacitance            | $V_{CE} = 25\text{ V}, f = 1\text{ MHz}, V_{GE} = 0\text{ V}$ | -    | 11000 | -    | pF   |
| $C_{oes}$ | Output capacitance           |   | -    | 610   | -    |      |
| $C_{res}$ | Reverse transfer capacitance |   | -    | 250   | -    |      |
| $Q_g$     | Total gate charge            | $V_{CC} = 520\text{ V}, I_C = 120\text{ A},$                  | -    | 420   | -    | nC   |
| $Q_{ge}$  | Gate-emitter charge          | $V_{GE} = 0\text{ to }15\text{ V}$                            | -    | 90    | -    |      |
| $Q_{gc}$  | Gate-collector charge        | (see Figure 30. Gate charge test circuit)                     | -    | 160   | -    |      |

**Table 5. IGBT switching characteristics (inductive load)**

| Symbol          | Parameter                    | Test conditions  | Min.  | Typ. | Max. | Unit |            |
|-----------------|------------------------------|--|---|------|------|------|------------|
| $t_{d(on)}$     | Turn-on delay time           | $V_{CE} = 400\text{ V}$ , $I_C = 120\text{ A}$ ,<br>$V_{GE} = 15\text{ V}$ , $R_G = 4.7\ \Omega$<br>(see Figure 29. Test circuit for inductive load switching) |   | 66   | -    | ns   |            |
| $t_r$           | Current rise time            |  |   | 38   | -    | ns   |            |
| $(di/dt)_{on}$  | Turn-on current slope        |  |   |      | 2500 | -    | A/ $\mu$ s |
| $t_{d(off)}$    | Turn-off-delay time          |  |   |      | 185  | -    | ns         |
| $t_f$           | Current fall time            |  |   |      | 85   | -    | ns         |
| $E_{on}^{(1)}$  | Turn-on switching energy     |  |   |      | 1.8  | -    | mJ         |
| $E_{off}^{(2)}$ | Turn-off switching energy    |  |   |      | 4.41 | -    | mJ         |
| $E_{ts}$        | Total switching energy       |  |   |      | 6.21 | -    | mJ         |
| $t_{d(on)}$     | Turn-on delay time           |  | $V_{CE} = 400\text{ V}$ , $I_C = 120\text{ A}$ ,<br>$V_{GE} = 15\text{ V}$ , $R_G = 4.7\ \Omega$ ,<br>$T_J = 175\text{ }^\circ\text{C}$<br>(see Figure 29. Test circuit for inductive load switching) |      | 62   | -    | ns         |
| $t_r$           | Current rise time            |  |   |      | 48   | -    | ns         |
| $(di/dt)_{on}$  | Turn-on current slope        |  |   |      | 2016 | -    | A/ $\mu$ s |
| $t_{d(off)}$    | Turn-off-delay time          |  |   |      | 187  | -    | ns         |
| $t_f$           | Current fall time            |  |   |      | 164  | -    | ns         |
| $E_{on}^{(1)}$  | Turn-on switching energy     |  |   |      | 4.4  | -    | mJ         |
| $E_{off}^{(2)}$ | Turn-off switching energy    |  |   |      | 6.0  | -    | mJ         |
| $E_{ts}$        | Total switching energy       |  |   |      | 10.4 | -    | mJ         |
| $t_{sc}$        | Short-circuit withstand time | $V_{CC} \leq 400\text{ V}$ , $V_{GE} = 13\text{ V}$ ,<br>$T_{Jstart} = 150\text{ }^\circ\text{C}$  |   | 10   |      | -    | $\mu$ s    |
|                 |                              | $V_{CC} \leq 400\text{ V}$ , $V_{GE} = 15\text{ V}$ ,<br>$T_{Jstart} = 150\text{ }^\circ\text{C}$  | 6   |      | -    |      |            |

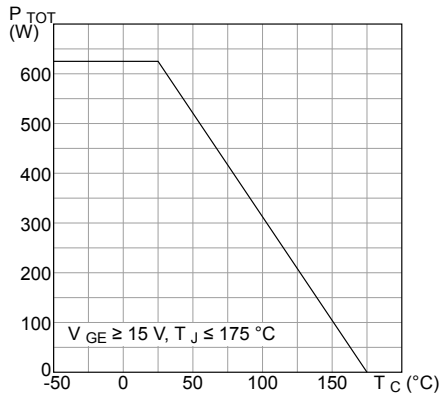
1. Including the reverse recovery of the diode.
2. Including the tail of the collector current.

**Table 6. Diode switching characteristics (inductive load)**

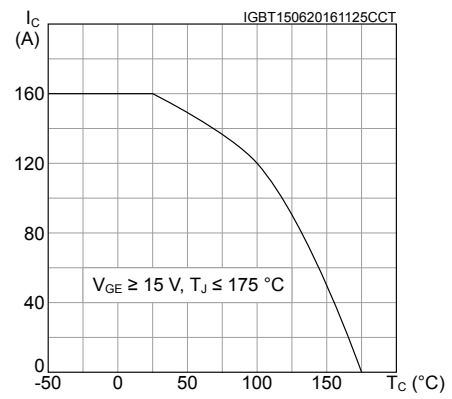
| Symbol       | Parameter  | Test conditions  | Min. | Typ. | Max. | Unit |            |
|--------------|--|--|------|------|------|------|------------|
| $t_{rr}$     | Reverse recovery time                                      | $I_F = 120\text{ A}$ , $V_R = 400\text{ V}$ ,<br>$V_{GE} = 15\text{ V}$ , $di/dt = 1000\text{ A}/\mu\text{s}$<br>(see Figure 29. Test circuit for inductive load switching)  | -    | 202  | -    | ns   |            |
| $Q_{rr}$     | Reverse recovery charge                                    |  |      | -    | 2.9  | -    | $\mu$ C    |
| $I_{rrm}$    | Reverse recovery current                                   |  |      | -    | 32.5 | -    | A          |
| $dI_{rr}/dt$ | Peak rate of fall of reverse recovery current during $t_b$ |  |      | -    | 500  | -    | A/ $\mu$ s |
| $E_{rr}$     | Reverse recovery energy                                    |  |      | -    | 500  | -    | $\mu$ J    |
| $t_{rr}$     | Reverse recovery time                                      | $I_F = 120\text{ A}$ , $V_R = 400\text{ V}$ ,<br>$V_{GE} = 15\text{ V}$ , $di/dt = 1000\text{ A}/\mu\text{s}$ ,<br>$T_J = 175\text{ }^\circ\text{C}$<br>(see Figure 29. Test circuit for inductive load switching) | -    | 320  | -    | ns   |            |
| $Q_{rr}$     | Reverse recovery charge                                    |  |      | -    | 11.2 | -    | $\mu$ C    |
| $I_{rrm}$    | Reverse recovery current                                   |  |      | -    | 62   | -    | A          |
| $dI_{rr}/dt$ | Peak rate of fall of reverse recovery current during $t_b$ |  |      | -    | 270  | -    | A/ $\mu$ s |
| $E_{rr}$     | Reverse recovery energy                                    |  |      | -    | 1710 | -    | $\mu$ J    |

## 2.1 Electrical characteristics (curves)

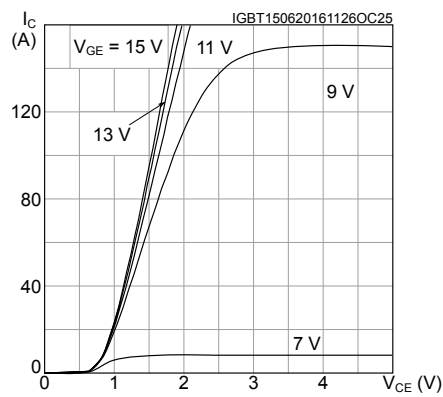
**Figure 1. Power dissipation vs case temperature**



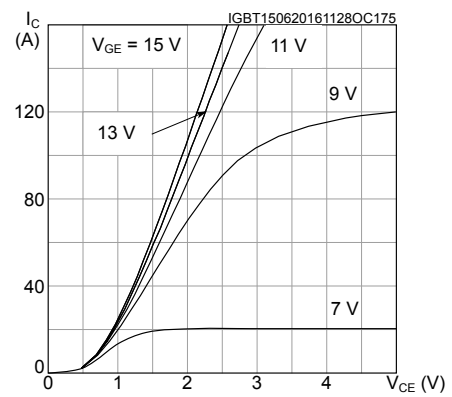
**Figure 2. Collector current vs case temperature**



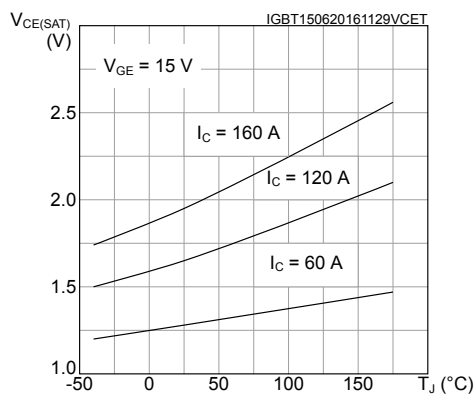
**Figure 3. Output characteristics (T<sub>J</sub> = 25 °C)**



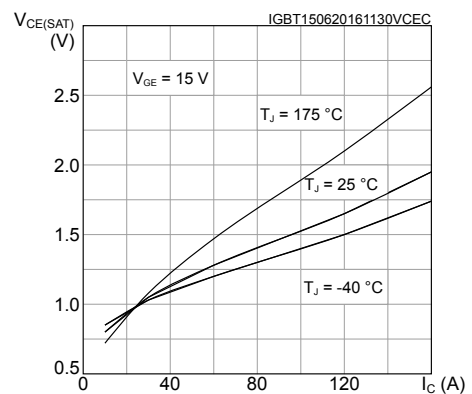
**Figure 4. Output characteristics (T<sub>J</sub> = 175 °C)**



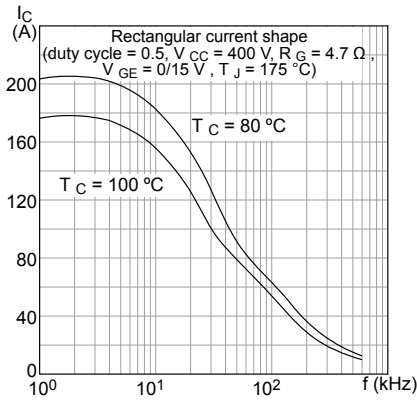
**Figure 5. V<sub>CE(sat)</sub> vs junction temperature**



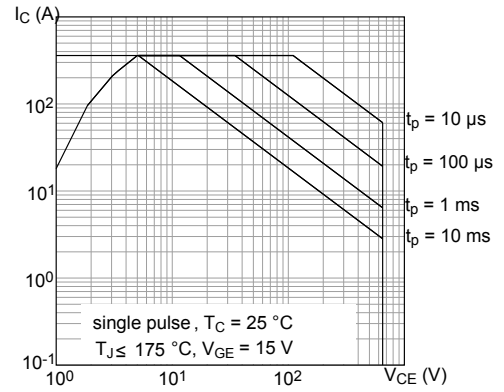
**Figure 6. V<sub>CE(sat)</sub> vs collector current**



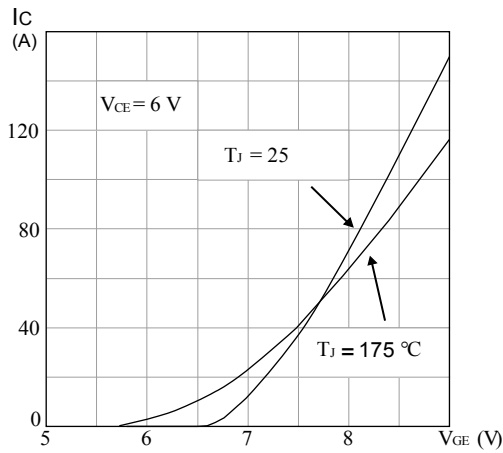
**Figure 7. Collector current vs switching frequency**



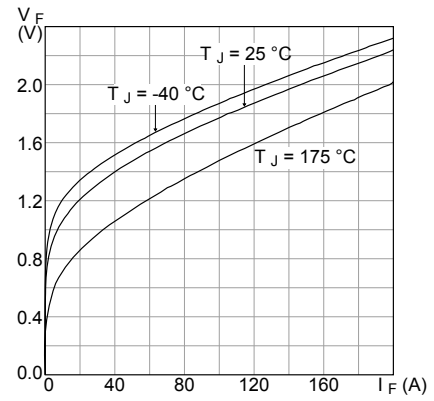
**Figure 8. Forward bias safe operating area**



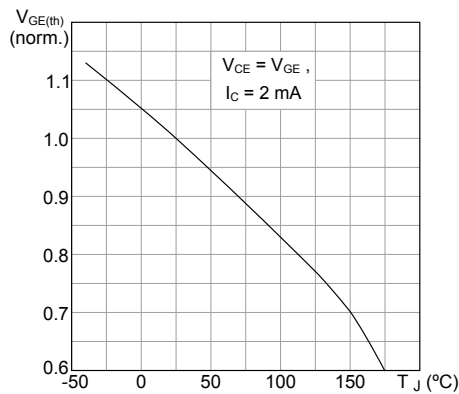
**Figure 9. Transfer characteristics**



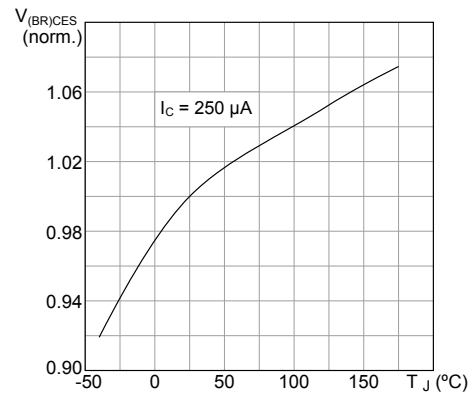
**Figure 10. Diode V<sub>F</sub> vs forward current**



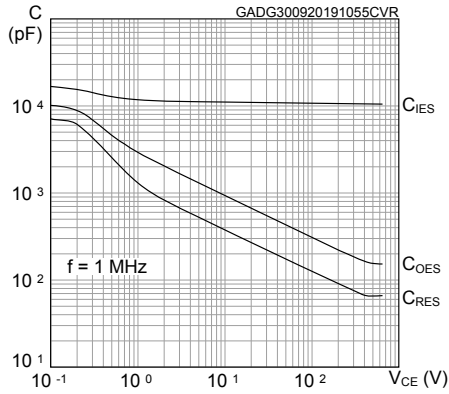
**Figure 11. Normalized V<sub>GE(th)</sub> vs junction temperature**



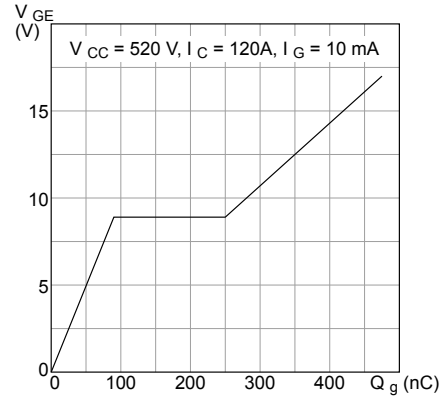
**Figure 12. Normalized V<sub>(BR)CES</sub> vs junction temperature**



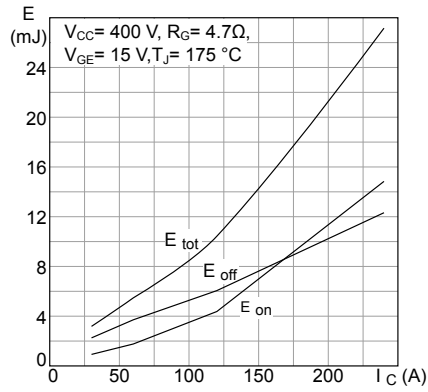
**Figure 13. Capacitance variations**



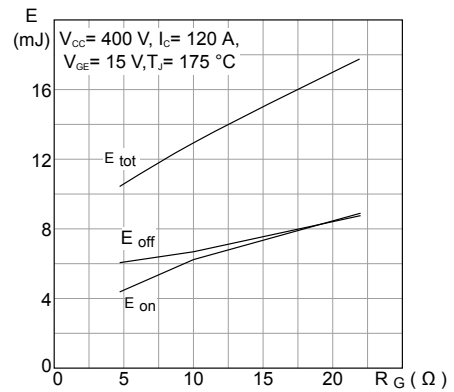
**Figure 14. Gate charge vs gate-emitter voltage**



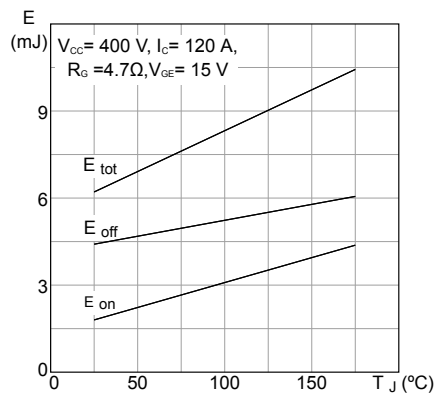
**Figure 15. Switching energy vs collector current**



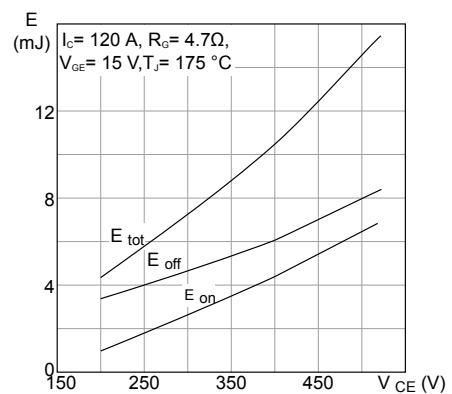
**Figure 16. Switching energy vs gate resistance**



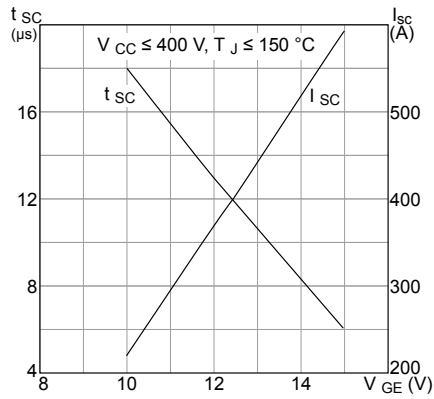
**Figure 17. Switching energy vs temperature**



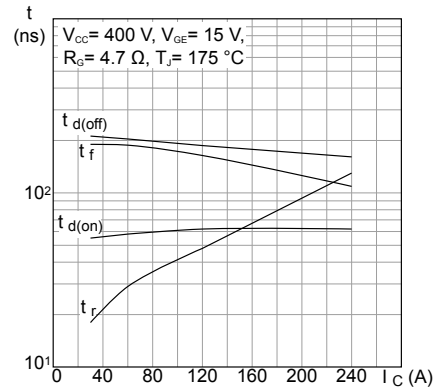
**Figure 18. Switching energy vs collector emitter voltage**



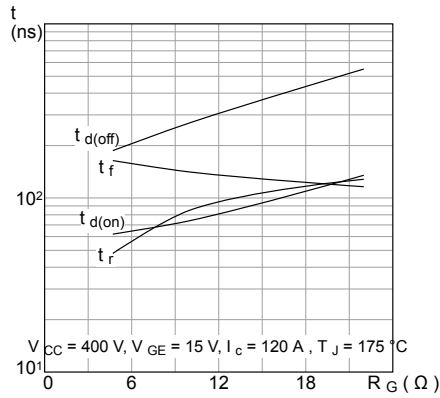
**Figure 19. Short circuit time and current vs  $V_{GE}$**



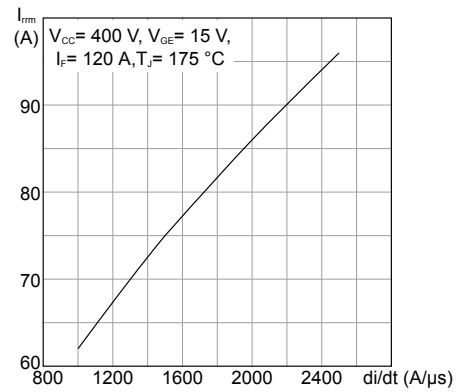
**Figure 20. Switching times vs collector current**



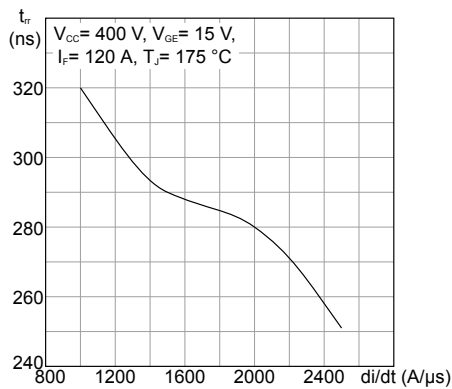
**Figure 21. Switching times vs gate resistance**



**Figure 22. Reverse recovery current vs diode current slope**



**Figure 23. Reverse recovery time vs diode current slope**



**Figure 24. Reverse recovery charge vs diode current slope**

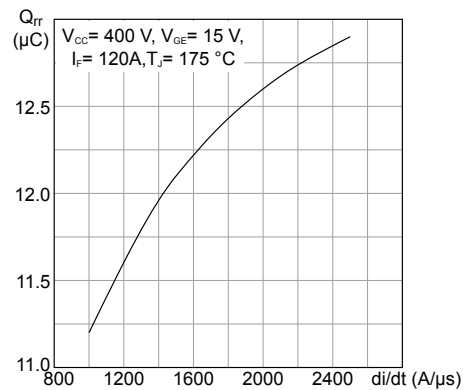




Figure 25. Reverse recovery energy vs diode current slope

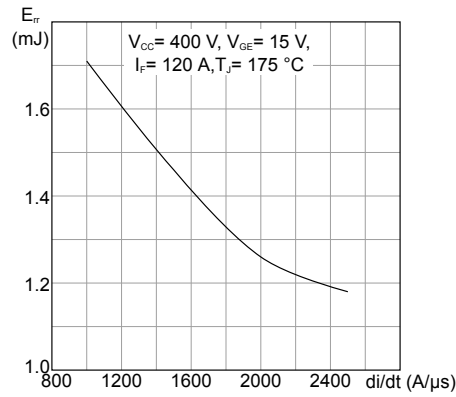


Figure 26. Thermal impedance for IGBT

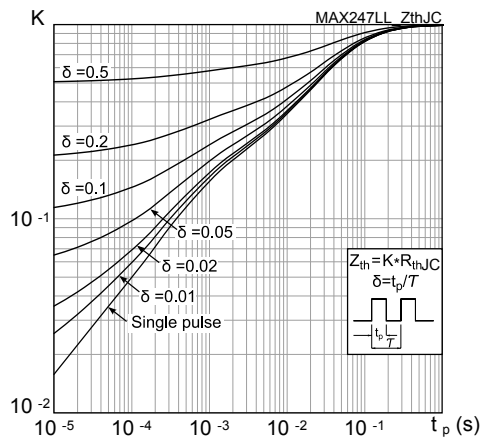
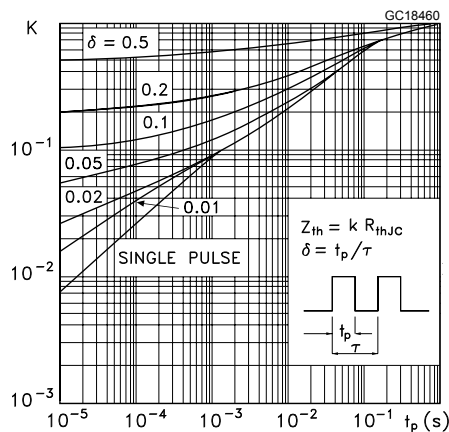
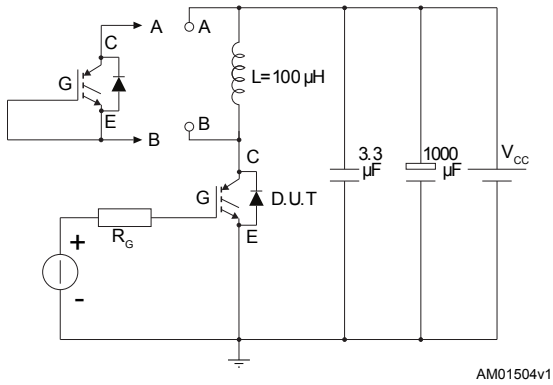
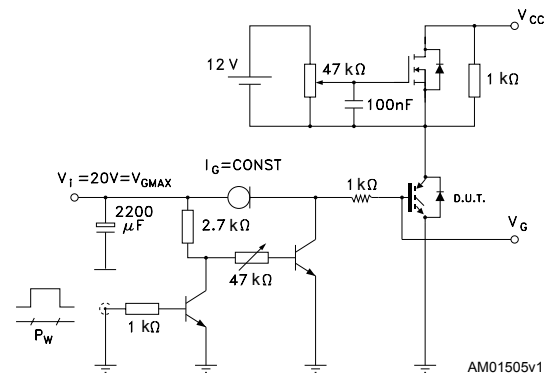
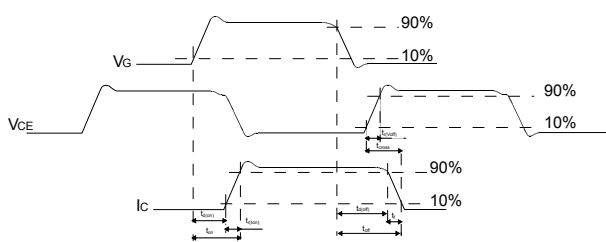
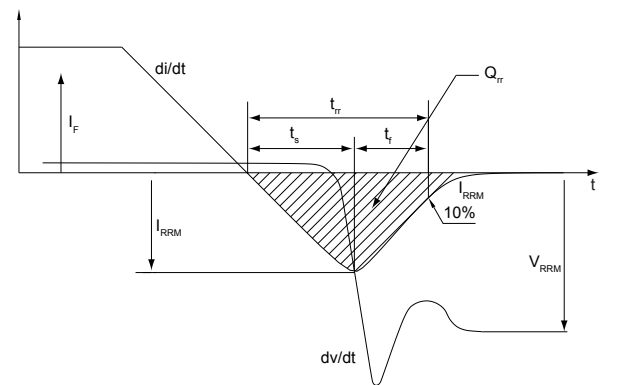


Figure 27. Thermal impedance for diode



### 3 Test circuits

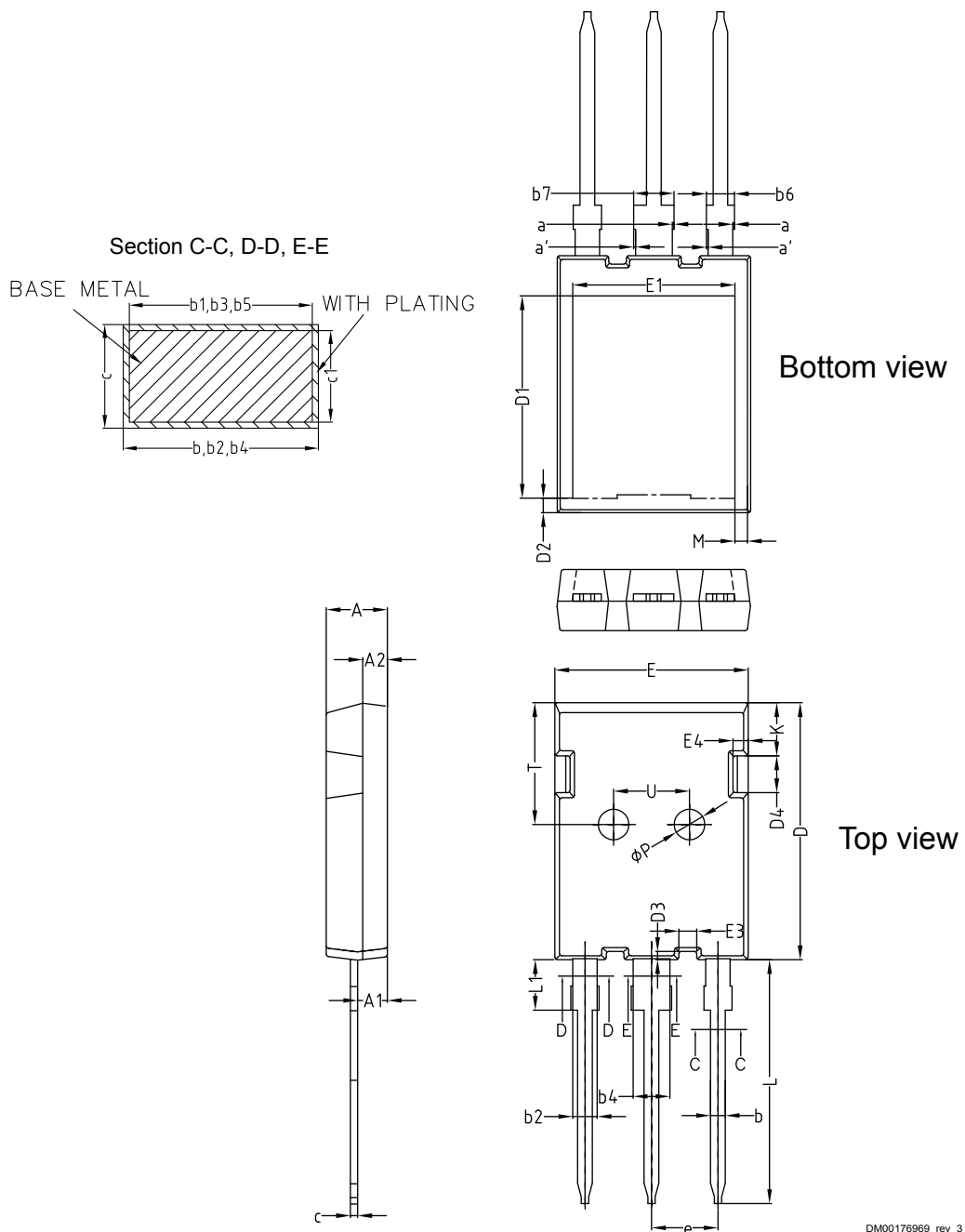
**Figure 28. Test circuit for inductive load switching**

**Figure 29. Gate charge test circuit**

**Figure 30. Switching waveform**

**Figure 31. Diode reverse recovery waveform**


## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

### 4.1 Max247 long leads package information

Figure 32. Max247 long leads package outline



DM00176969\_rev\_3

**Table 7. Max247 long leads package mechanical data**

| Dim. | mm    |       |       |
|------|-------|-------|-------|
|      | Min.  | Typ.  | Max.  |
| A    | 4.90  | 5.00  | 5.10  |
| A1   | 2.31  | 2.41  | 2.51  |
| A2   | 1.90  | 2.00  | 2.10  |
| a    | 0     |       | 0.15  |
| a'   | 0     |       | 0.15  |
| b    | 1.16  |       | 1.26  |
| b1   | 1.15  | 1.20  | 1.22  |
| b2   | 1.96  |       | 2.06  |
| b3   | 1.95  | 2.00  | 2.02  |
| b4   | 2.96  |       | 3.06  |
| b5   | 2.95  | 3.00  | 3.02  |
| b6   |       |       | 2.25  |
| b7   |       |       | 3.25  |
| c    | 0.59  |       | 0.66  |
| c1   | 0.58  | 0.60  | 0.62  |
| D    | 20.90 | 21.00 | 21.10 |
| D1   | 16.25 | 16.55 | 16.85 |
| D2   | 1.05  | 1.17  | 1.35  |
| D3   | 0.58  | 0.68  | 0.78  |
| D4   | 2.90  | 3.00  | 3.10  |
| E    | 15.70 | 15.80 | 15.90 |
| E1   | 13.10 | 13.26 | 13.50 |
| E3   | 1.35  | 1.45  | 1.55  |
| E4   | 1.14  | 1.24  | 1.34  |
| e    | 5.34  | 5.44  | 5.54  |
| K    | 4.25  | 4.35  | 4.45  |
| L    | 19.80 | 19.92 | 20.10 |
| L1   | 3.90  |       | 4.30  |
| M    | 0.70  |       | 1.30  |
| P    | 2.40  | 2.50  | 2.60  |
| T    | 9.80  |       | 10.20 |
| U    | 6.00  |       | 6.40  |

## Revision history

**Table 8. Document revision history**

| Date        | Revision | Changes   |
|-------------|----------|---|
| 12-Aug-2016 | 1        | First release.  |
| 12-Dec-2016 | 2        | Document status promoted from preliminary to production data.<br>Minor text changes.  |
| 24-Aug-2017 | 3        | Updated features and title in cover page.<br>Updated <i>Table 4: "Static characteristics"</i> .<br>Minor text changes.  |
| 08-Oct-2019 | 4        | Updated <i>Table 4. Dynamic characteristics</i> .<br>Updated <i>Figure 9. Forward bias safe operating area</i> and <i>Figure 14. Capacitance variations</i> .<br>Minor text changes |
| 16-Nov-2022 | 5        | Updated <a href="#">Section 4.1 Max247 long leads package information</a> .<br>Minor text changes.  |

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